

FLUX, SOLDER PASTE, AND METHOD FOR PRODUCING JOINED STRUCTURE

ABSTRACT

A flux of the present invention is a flux used for soldering. The flux includes: at least one selected from the group consisting of a fatty alcohol having one hydroxy group and being solid at 20°C and a fatty acid ester being solid at 20°C; a liquid solvent having one or more and three or less hydroxy groups and being liquid at 20°C; and a solid solvent having two or more and four or less hydroxy groups and being solid at 20°C. The flux includes no thixotropic agent or includes 20.0 mass% or less of a thixotropic agent based on the entire flux.